



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP A-U200-A Unified Threat Management Appliance (JD275A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		3
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances	0
---	---

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 1, and then remove mounting angle 1.
2. Unscrew the screws on card 2, and then remove card 2.
3. Unscrew the screws on filler panel 3, and then remove filler panel 3.
4. Unscrew the screws on top cover 4, and remove top cover 4.
5. Remove all of the inner cables.
6. Unscrew the screws on power supply PCB 8, and remove power supply PCB 8.
7. Unscrew the screws on PCB 10, and remove PCB 10.
8. Remove plastic panel 11 from the chassis
9. Unscrew the screws on fan 7, and then remove fan 7.
10. Remove rocker switch 6 from the chassis.
11. Remove Power Connector 5 from the chassis.
12. Remove all of the labels.
13. Unscrew the screws on PCB 2-4, and then remove pulled handle 2-1, washer2-5, PCB 2-4.
14. Remove insulation pad 2-3 from bottom cover 2-2
15. Remove shielding finger 2-6 from front panel 2-2.
16. Remove shielding finger 3-2 from filler panel 3-1.
17. Remove film 11-2 from plastic panel 11-1.
18. Remove film 11-3 from plastic panel 11-1.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

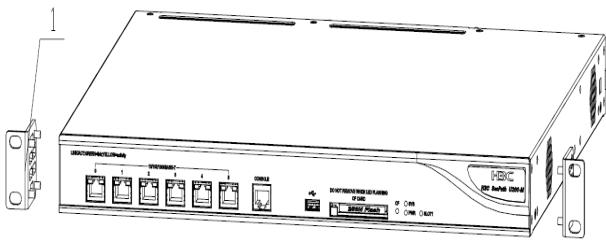


Figure 1 Remove mounting angle 1

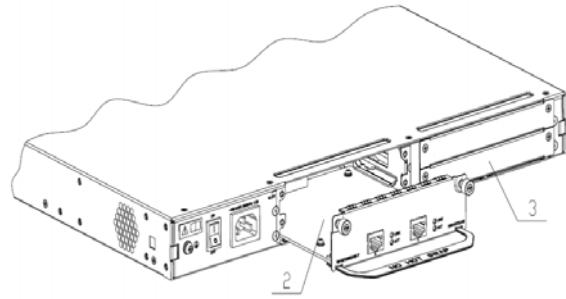


Figure 2 Rear of the product

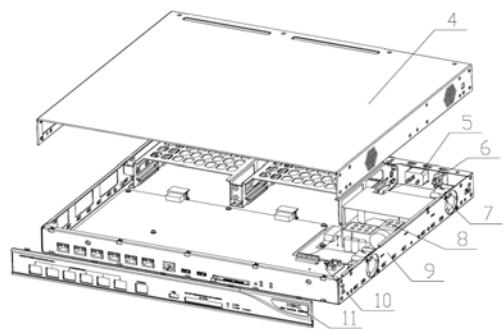


Figure 3 Treatments to the product

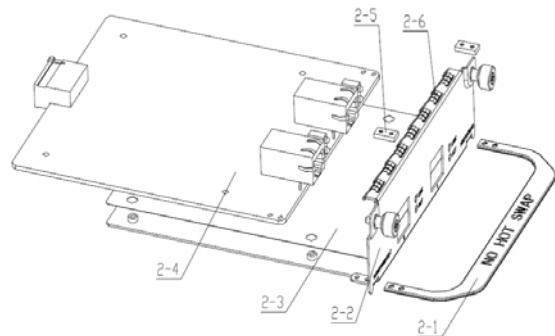


Figure 4 Treatments to card 2

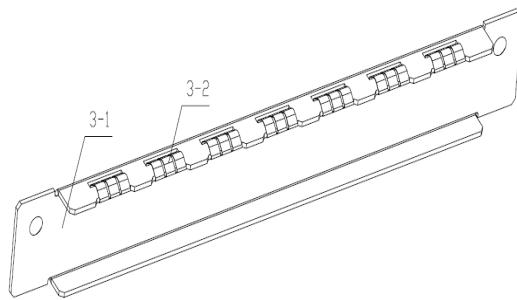


Figure 5 Treatments to filler panel 3

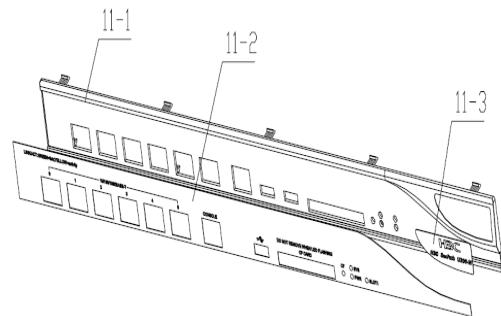


Figure 6 Treatments to plastic panel 11